

QRSS-8P-1800

0.4–1.8 GHz Direct Down-Conversion RF Front-End

DESCRIPTION

The QRSS-8P-1800 is a fully integrated, reconfigurable switch-capacitor mixer-first RF receiver front-end operating from 0.4 to 1.8 GHz. Using an innovative eight-path quarter-rate subsampling (QRSS) architecture, it achieves direct (zero-IF) down-conversion and wideband 50-Ω impedance matching simultaneously—without an external LNA.

The device exploits the third harmonic of the QRSS sampling clock (f_s) and an eight-path passive mixer transparency property to translate the 50-Ω antenna impedance directly to the RF port. The sampling frequency is three times lower than the input RF frequency, dramatically reducing VCO and clock-distribution power by up to 89% versus conventional RF-sampling architectures.

Implemented in 65 nm CMOS process and occupying only 0.32 mm², the QRSS-8P-1800 is ideally suited for battery-powered IoT nodes, smart utility networks, rail communications, healthcare wearables, and software-defined radio platforms requiring sub-6 GHz multi-standard coverage.

KEY FEATURES

- Frequency range: 0.4–1.8 GHz
- Direct (zero-IF) quadrature down-conversion
- Eight-path passive CMOS switch-capacitor mixer
- No external Matching required — 50-Ω input match at mixer
- Sampling frequency 3× lower than RF (89% VCO power saving vs. RF sampling)
- Noise Figure: 4.7 dB
- Conversion Gain: 22 dB
- IB-IIP₃: -1 dBm | OB-IIP₃: +8 dBm
- 3-dB Bandwidth: 90 MHz
- Mixer power: 800 μW
- BBLNA power: 23 mW
- Active area: 0.32 mm² in 65 nm CMOS
- Supply voltage: 1.2 V (core)

APPLICATIONS

Application	Relevant Bands	Notes
Smart Utility Networks (SUN)	400–900 MHz	Long battery life, sub-GHz LPWAN
Rail Communications & Control (RCC)	400–900 MHz	Robust wideband reconfigurability
Healthcare & Body-Area Wearables	400 MHz, 915 MHz, 2.4 GHz*	Ultra-low mixer power (800 μW)
Industrial IoT Monitoring	Sub-1 GHz / ISM 2.4 GHz*	Wide-band, low-power platform
Cellular Band Scanning / CAT-M	700–1800 MHz	Direct down-conversion, no IF filter

ELECTRICAL SPECIFICATIONS

TA = 27°C, VDD = 1.2 V, unless otherwise noted.

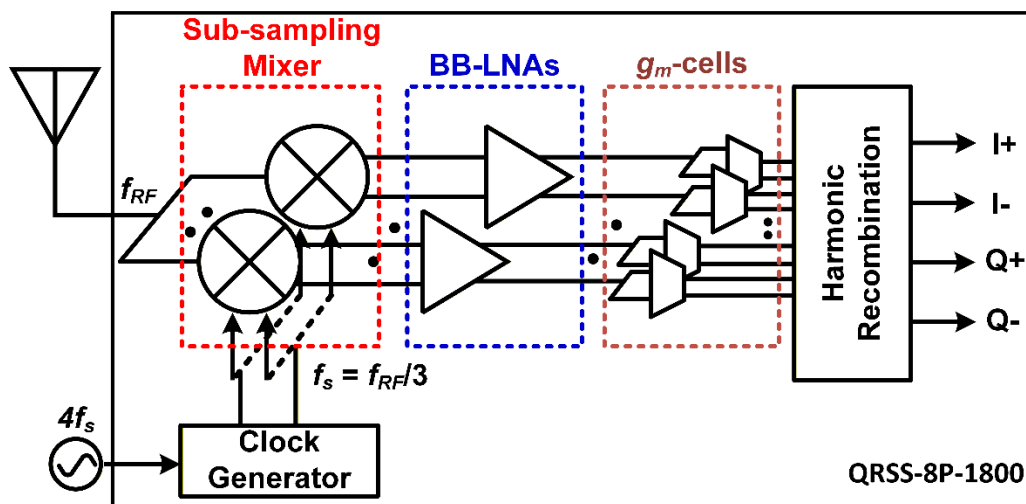
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
RF Frequency Range	f_{RF}	0.4	—	1.8	GHz	
Sampling Frequency	f_s	0.13	—	0.6	GHz	
Noise Figure	NF	4.7	—	8.0	dB	0.4 – 1.8 GHz band
Conversion Gain	G	—	22	—	dB	±1.5 dB variation over band
3-dB Bandwidth (Baseband)	BW	—	90	—	MHz	$f_{RF} = 1.47$ GHz

In-Band IIP ₃	IB-IIP ₃	—	−1	—	dBm	$\Delta f = 1 \text{ MHz}$
Out-of-Band IIP ₃	OB-IIP ₃	—	+8	—	dBm	$\Delta f = 150 \text{ MHz}$
Input P1dB	IP1dB	—	−15	—	dBm	$f_{RF} = 1.47 \text{ GHz}$
Input Return Loss (at $3f_s$)	S_{11}	−35	−20	−10	dB	Matched to 50Ω
Harmonic Rejection (1st)	HR ₁	—	36	—	dB	vs. 3rd harmonic
Supply Voltage (Core)	VDD	—	1.2	—	V	

POWER CONSUMPTION

Block	Power	Supply	Notes
Eight-Path Subsampling Mixer	800 μW	1.2 V	Constant over 0.4–1.8 GHz
Baseband LNA (BBLNA)	23 mW	1.2 V	At $V_{ctrl} = 0.4 \text{ V}$ for IIP ₃ = −1 dBm
g_m -Cell	3 mW	1.2 V	Harmonic recombination stage
Nonoverlapping Clock Generator	2–9.2 mW	1.2 V	Scales with f_s (0.13–0.6 GHz)

ARCHITECTURE OVERVIEW



Signal Path

- Off-chip RF band-select filter suppresses blockers at odd harmonics of f_s
- Eight-path 12.5%-duty-cycle passive switch-capacitor mixer down-converts RF at the 3rd harmonic of f_s directly to zero-IF
- Differential CMOS inverter-based noise-cancelling BBLNA provides gain and baseband impedance
- g_m -cells duplicate and amplify BB outputs for harmonic recombination
- Harmonic recombination extracts I/Q at $3f_s$ and attenuates 1st- and 5th-harmonic spurs

Impedance Matching

- No external IF matching network required—simplifies PCB layout
- $S_{11} < -10 \text{ dB}$ maintained across full 0.4–1.8 GHz band

FREQUENCY PLAN

Parameter	Formula / Value	Example ($f_{RF} = 1.47$ GHz, $k = 1$)
Sampling Frequency (f_s)	$f_{RF} / (2k + 1) \mid k = 1, 2, 3 \dots$	490 MHz
Effective LO Frequency ($3f_s$)	$3 \times f_s$	1.47 GHz
Baseband Frequency (f_{BB})	$f_{RF} - n \cdot f_s \mid n = 1, 3, 5 \dots$	20 MHz ($n = 3$)

ABSOLUTE MAXIMUM RATINGS

Stress above listed limits may permanently damage the device. Functional operation at these limits is not implied.

Parameter	Limit	Unit
Core Supply Voltage (VDD)	1.2 + 0.3	V
I/O / Buffer Supply Voltage	2.5 + 0.5	V
Operating Temperature	–40 to +85	°C
ESD Rating (HBM)	2000	V

DEVICE INFORMATION

Parameter	Value
Part Number	QRSS-8P-1800
Technology	65 nm CMOS (TSMC 1P9M)
Die Size (Active)	0.32 mm ²
Die Supply (Core)	1.2 V
Die Supply (I/O)	2.5 V
Package	QFN40
Operating Temperature Range	–40°C to +85°C

DESIGN SUPPORT & RELATED RESOURCES

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